

Title (en)

Process and device for applying glue to packaging material

Title (de)

Verfahren und Vorrichtung zum Beleimen von Verpackungsmaterial

Title (fr)

Procédé et dispositif pour appliquer de l'adhésif à matériel d'emballage

Publication

EP 1437303 B2 20121212 (DE)

Application

EP 03029332 A 20031219

Priority

DE 10300485 A 20030108

Abstract (en)

[origin: EP1437303A2] As hot-melt glue is transferred onto a length of fabric for blanks, transfer of glue depends on the speed at which the length of fabric is feed through and on other parameters. Glue pressure applied to the glue is controlled in accordance with the movement of the length of material to be glued. This is done via a pressure control valve (37) linked to a central machine controller (31). An Independent claim is also included for a device for applying hot-melt glue/adhesive on a packaging production line.

IPC 8 full level

B65B 51/02 (2006.01); **B05C 11/00** (2006.01); **B05C 11/10** (2006.01); **B05D 1/26** (2006.01); **B05D 7/24** (2006.01); **B31B 50/62** (2017.01)

CPC (source: EP US)

B05C 11/1005 (2013.01 - EP US); **B05C 11/1023** (2013.01 - EP US); **B65B 51/023** (2013.01 - EP US); **B05C 5/027** (2013.01 - EP US); **B05C 11/1013** (2013.01 - EP US); **B31B 50/624** (2017.08 - EP US)

Citation (opposition)

Opponent :

- US 5893490 A 19990413 - GNYP STEVEN M [US]
- US 5979794 A 19991109 - DEFILLIPI MICHAEL E [US], et al
- US 4988015 A 19910129 - PRICE RICHARD P [US]

Cited by

WO2008100726A1; CN104118139A; CN106000792A; DE102008027259A1; EP2319767A1; CN104118604A; DE102013225051A1; US8690744B2; US7770760B2; WO2009146766A1; WO2007093288A1; US7874456B2; EP1984163A1; EP3138785B1; EP3138785A1

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DOCDB simple family (publication)

EP 1437303 A2 20040714; **EP 1437303 A3 20060201**; **EP 1437303 B1 20090527**; **EP 1437303 B2 20121212**; AT E432224 T1 20090615; BR PI0400103 A 20041228; BR PI0400103 B1 20141216; CN 100393588 C 20080611; CN 1517274 A 20040804; DE 50311548 D1 20090709; JP 2004210405 A 20040729; JP 4510472 B2 20100721; US 2004161531 A1 20040819

DOCDB simple family (application)

EP 03029332 A 20031219; AT 03029332 T 20031219; BR PI0400103 A 20040107; CN 200410001454 A 20040108; DE 50311548 T 20031219; JP 2004001987 A 20040107; US 75110204 A 20040105